



# SHENZHEN FAITH TECHNOLOGY CO.,LTD

## SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

### SS5150BF THRU SS5200BF

VOLTAGE RANGE  
CURRENT

150 to 200 Volts  
5.0 Ampere

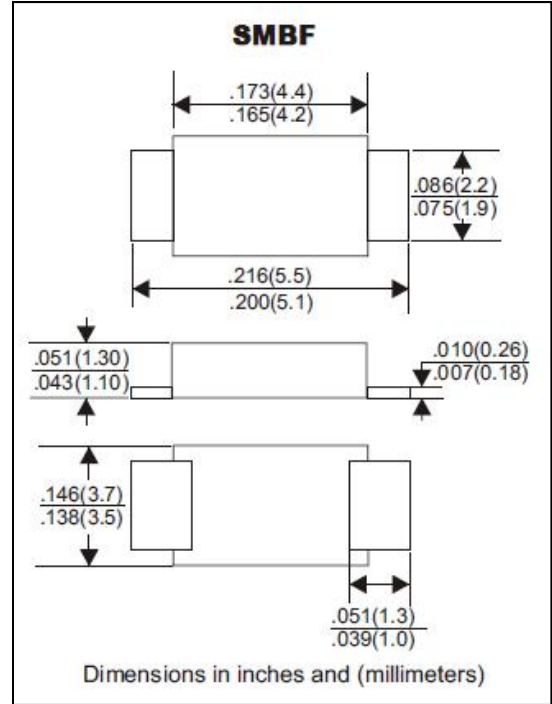


### Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V - 0 For surface mounted applications
- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- Built - in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 260 C/10 seconds at terminals

### Mechanical Data

- Case: Transfer molded plastic
- Epoxy: UL 94V - 0 rate flame retardant
- Lead :Solder plated, solderable per MIL -STD -750 method 2026
- Polarity: Color band denotes cathode end
- Weight: 0.002ounce, 0.066 gram



### Maximum Ratings and Electrical Characteristics

- Ratings at 25°C ambient temperature unless otherwise specified
- Single phase, half wave, 60Hz, resistive or inductive load
- For capacitive load derate current by 20%

TYPE NUMBER	SYMBOLS	SS53150BF	SS5200BF	UNIT
Device Marking Code		SS515	SS520	
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	150	200	Volts
Maximum RMS Voltage	$V_{RMS}$	105	140	Volts
Maximum DC Blocking Voltage	$V_{DC}$	150	200	Volts
Maximum Average Forward Rectified Current at $T_{see}$ figure 1 $T_c = 75^\circ C$	$I_{(AV)}$	5.0		Amps
Peak Forward Surge Current 8.3 ms single half sine - wave superimposed on rated load (JEDEC method)	$I_{FSM}$	100		Amps
Maximum Instantaneous Forward Voltage @ 5.0A <sup>(Note1)</sup>	$V_F$	0.95		Volts
Maximum DC Reverse Current at rated DC Blocking Voltage per element	$T_A = 25^\circ C$	0.1		mA
	$T_A = 100^\circ C$	10		
Typical Thermal Resistance <sup>(Note 2)</sup>	$R_{\theta JA}$	135		$^\circ C/W$
	$R_{\theta JL}$	25		
Diode junction capacitance <sup>(Note 3)</sup>	$C_j$	110		pF
Operating Junction Temperature	$T_j$	-40 to +150		$^\circ C$
Storage Temperature Range	$T_{STG}$	-40 to +150		$^\circ C$

#### Notes:

- Pulse test: 300µs pulse width, 1% duty cycle.
- Thermal resistance from Junction to ambient and from junction to lead mounted on PCB. with 0.3 × 0.3 "(8.0 × 8.0mm) copper pad areas.
- f = 1MHz and applied 4V DC reverse voltage.

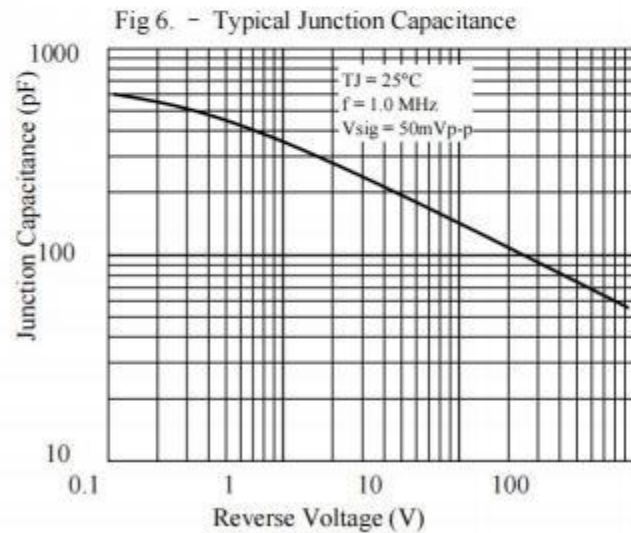
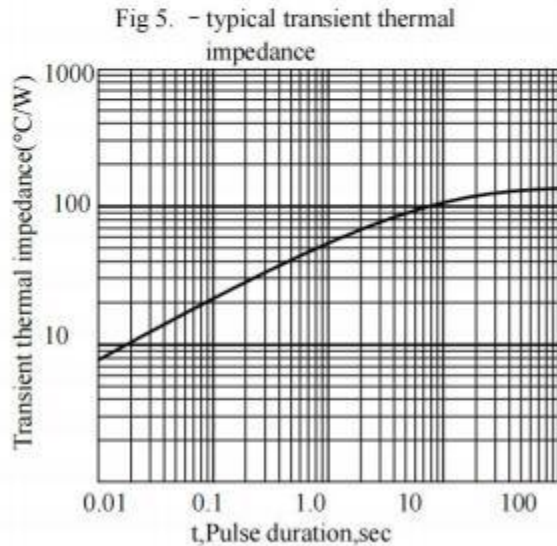
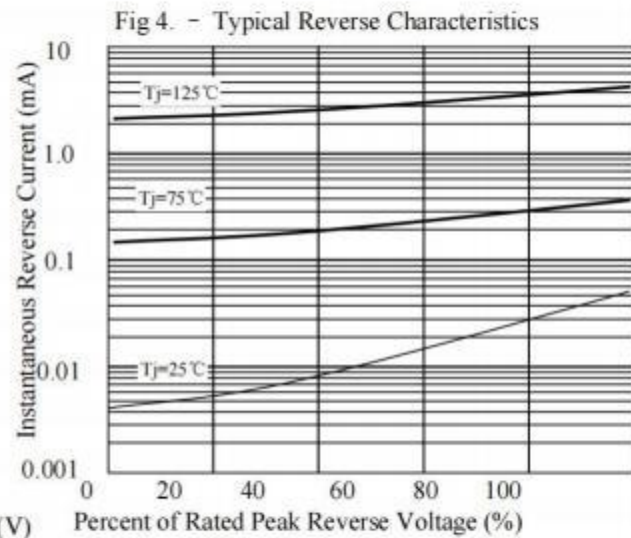
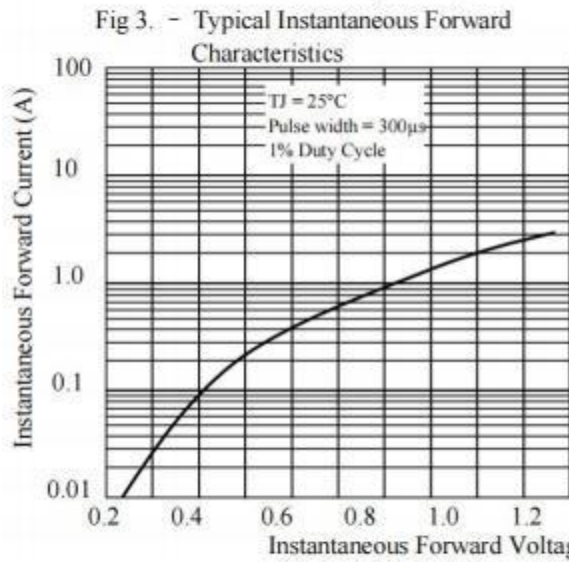
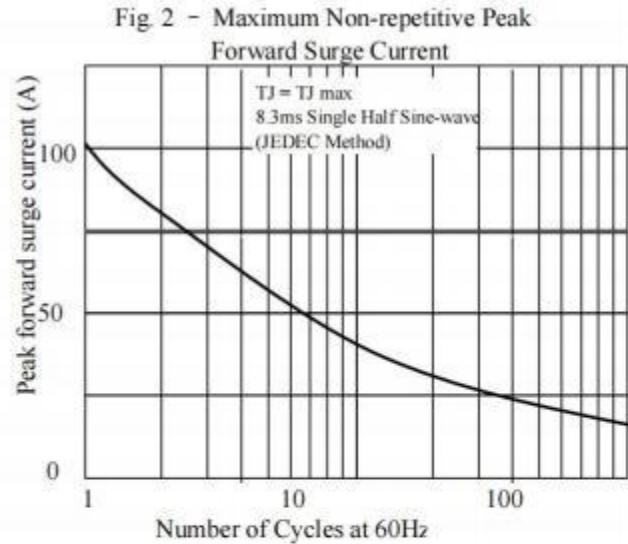
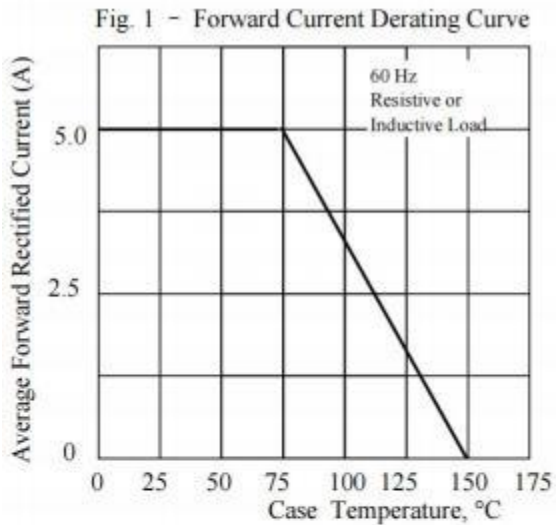


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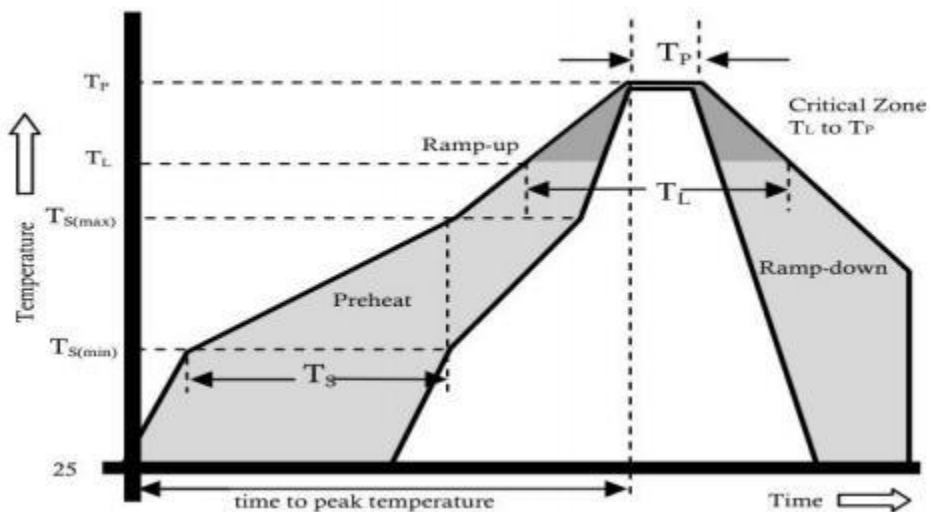
150 to 200 Volts  
5.0 Ampere

Ratings and Characteristic Curves ( $T_A = 25^\circ\text{C}$  unless otherwise noted)





Reflow Profile



Reflow Condition		Pb - Free Assembly
Pre Heat	Temperature Min.	+150°C
	Temperature Max.	+200°C
	Time(Min to Max)	60 -180 secs.
Average ramp up rate(Liquidus Temp( $T_L$ ) to peak)		3°C/sec. Max.
$T_S(max)$ to $T_L$ - Ramp -up Rate		3°C/sec. Max.
Reflow	Temperature ( $T_L$ )( Liquidus)	+217°C
	Temperature ( $T_L$ )	60 -150 secs.
Peak Temp ( $T_P$ )		+(260+0/ -5 ) °C
Time within 5 °C of actual Peak Temp ( $T_P$ )		25 secs.
Ramp -down Rate		6°C/sec. Max.
Time 25°C to peak Temp ( $T_P$ )		8 min. Max.
Do not exceed		+260°C